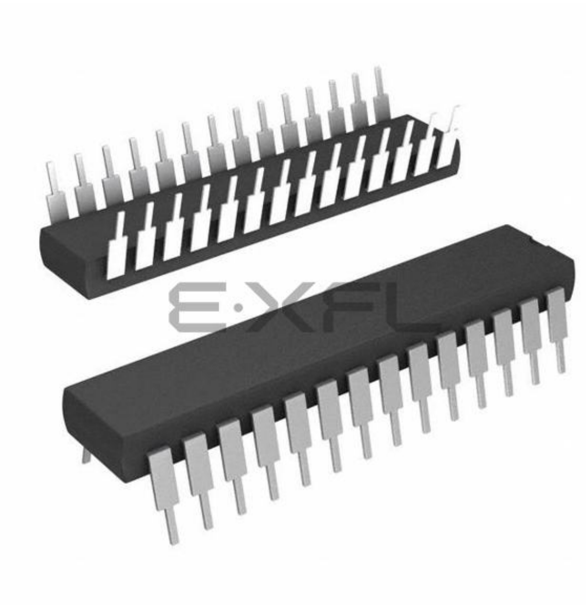

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2520-i-sp

TABLE 5-2: PIC18F2420/2520/4420/4520 REGISTER FILE SUMMARY (CONTINUED)

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Details on page:
SPBRGH	EUSART Baud Rate Generator Register High Byte								0000 0000	51, 206
SPBRG	EUSART Baud Rate Generator Register Low Byte								0000 0000	51, 206
RCREG	EUSART Receive Register								0000 0000	51, 213
TXREG	EUSART Transmit Register								0000 0000	51, 211
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	51, 202
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	51, 203
EEADR	EEPROM Address Register								0000 0000	51, 74, 83
EEDATA	EEPROM Data Register								0000 0000	51, 74, 83
EECON2	EEPROM Control Register 2 (not a physical register)								0000 0000	51, 74, 83
EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	xx-0 x000	51, 75, 84
IPR2	OSCFIP	CMIP	—	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	11-1 1111	52, 101
PIR2	OSCFIF	CMIF	—	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	00-0 0000	52, 97
PIE2	OSCFIE	CMIE	—	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	00-0 0000	52, 99
IPR1	PSPIP(2)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	1111 1111	52, 100
PIR1	PSPIF(2)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	52, 96
PIE1	PSPIE(2)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	52, 98
OSCTUNE	INTSRC	PLLEN(3)	—	TUN4	TUN3	TUN2	TUN1	TUN0	0q-0 0000	27, 52
TRISE(2)	IBF	OBF	IBOV	PSPMODE	—	TRISE2	TRISE1	TRISE0	0000 -111	52, 118
TRISD(2)	PORTD Data Direction Register								1111 1111	52, 114
TRISC	PORTC Data Direction Register								1111 1111	52, 111
TRISB	PORTB Data Direction Register								1111 1111	52, 108
TRISA	TRISA7(5)	TRISA6(5)	PORTA Data Direction Register						1111 1111	52, 105
LATE(2)	—	—	—	—	—	PORTE Data Latch Register (Read and Write to Data Latch)			---- -xxx	52, 117
LATD(2)	PORTD Data Latch Register (Read and Write to Data Latch)								xxxx xxxx	52, 114
LATC	PORTC Data Latch Register (Read and Write to Data Latch)								xxxx xxxx	52, 111
LATB	PORTB Data Latch Register (Read and Write to Data Latch)								xxxx xxxx	52, 108
LATA	LATA7(5)	LATA6(5)	PORTA Data Latch Register (Read and Write to Data Latch)						xxxx xxxx	52, 105
PORTE	—	—	—	—	RE3(4)	RE2(2)	RE1(2)	RE0(2)	---- xxxx	52, 117
PORTD(2)	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	52, 114
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	52, 111
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	52, 108
PORTA	RA7(5)	RA6(5)	RA5	RA4	RA3	RA2	RA1	RA0	xx0x 0000	52, 105

Legend: x = unknown, u = unchanged, – = unimplemented, q = value depends on condition. Shaded cells are unimplemented, read as '0'.

Note 1: The SBOREN bit is only available when the BOREN<1:0> Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 4.4 "Brown-out Reset (BOR)"**.

2: These registers and/or bits are not implemented on 28-pin devices and are read as '0'. Reset values are shown for 40/44-pin devices; individual unimplemented bits should be interpreted as '-'.

3: The PLLEN bit is only available in specific oscillator configurations; otherwise, it is disabled and reads as '0'. See **Section 2.6.4 "PLL in INTOSC Modes"**.

4: The RE3 bit is only available when Master Clear Reset is disabled (MCLRE Configuration bit = 0); otherwise, RE3 reads as '0'. This bit is read-only.

5: RA6/RA7 and their associated latch and direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

EXAMPLE 6-3: WRITING TO FLASH PROGRAM MEMORY

```
               MOVLW   D'64                  ; number of bytes in erase block
               MOVWF   COUNTER
               MOVLW   BUFFER_ADDR_HIGH      ; point to buffer
               MOVWF   FSR0H
               MOVLW   BUFFER_ADDR_LOW
               MOVWF   FSR0L
               MOVLW   CODE_ADDR_UPPER       ; Load TBLPTR with the base
               MOVWF   TBLPTRU               ; address of the memory block
               MOVLW   CODE_ADDR_HIGH
               MOVWF   TBLPTRH
               MOVLW   CODE_ADDR_LOW
               MOVWF   TBLPTRL
READ_BLOCK
               TBLRD*+                       ; read into TABLAT, and inc
               MOVF    TABLAT, W             ; get data
               MOVWF   POSTINC0              ; store data
               DECFSZ  COUNTER               ; done?
               BRA     READ_BLOCK            ; repeat
MODIFY_WORD
               MOVLW   DATA_ADDR_HIGH        ; point to buffer
               MOVWF   FSR0H
               MOVLW   DATA_ADDR_LOW
               MOVWF   FSR0L
               MOVLW   NEW_DATA_LOW          ; update buffer word
               MOVWF   POSTINC0
               MOVLW   NEW_DATA_HIGH
               MOVWF   INDF0
ERASE_BLOCK
               MOVLW   CODE_ADDR_UPPER       ; load TBLPTR with the base
               MOVWF   TBLPTRU               ; address of the memory block
               MOVLW   CODE_ADDR_HIGH
               MOVWF   TBLPTRH
               MOVLW   CODE_ADDR_LOW
               MOVWF   TBLPTRL
               BSF     EECON1, EEPGD         ; point to Flash program memory
               BCF     EECON1, CFGS          ; access Flash program memory
               BSF     EECON1, WREN          ; enable write to memory
               BSF     EECON1, FREE          ; enable Row Erase operation
               BCF     INTCON, GIE           ; disable interrupts
               MOVLW   55h
Required       MOVWF   EECON2                ; write 55h
Sequence       MOVLW   0AAh
               MOVWF   EECON2                ; write 0AAh
               BSF     EECON1, WR            ; start erase (CPU stall)
               BSF     INTCON, GIE           ; re-enable interrupts
               TBLRD*-                       ; dummy read decrement
               MOVLW   BUFFER_ADDR_HIGH      ; point to buffer
               MOVWF   FSR0H
               MOVLW   BUFFER_ADDR_LOW
               MOVWF   FSR0L
WRITE_BUFFER_BACK
               MOVLW   D’32                  ; number of bytes in holding register
               MOVWF   COUNTER
WRITE_BYTE_TO_HREGS
               MOVFF   POSTINC0, WREG        ; get low byte of buffer data
               MOVWF   TABLAT                ; present data to table latch
               TBLWT+*                       ; write data, perform a short write
                                             ; to internal TBLWT holding register.
               DECFSZ  COUNTER               ; loop until buffers are full
               BRA     WRITE_WORD_TO_HREGS
```


NOTES:

14.0 TIMER3 MODULE

The Timer3 module timer/counter incorporates these features:

- Software selectable operation as a 16-bit timer or counter
- Readable and writable 8-bit registers (TMR3H and TMR3L)
- Selectable clock source (internal or external) with device clock or Timer1 oscillator internal options
- Interrupt-on-overflow
- Module Reset on CCP Special Event Trigger

A simplified block diagram of the Timer3 module is shown in Figure 14-1. A block diagram of the module's operation in Read/Write mode is shown in Figure 14-2.

The Timer3 module is controlled through the T3CON register (Register 14-1). It also selects the clock source options for the CCP modules (see **Section 15.1.1 "CCP Modules and Timer Resources"** for more information).

REGISTER 14-1: T3CON: TIMER3 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{\text{T3SYNC}}$	TMR3CS	TMR3ON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **RD16:** 16-Bit Read/Write Mode Enable bit
1 = Enables register read/write of Timer3 in one 16-bit operation
0 = Enables register read/write of Timer3 in two 8-bit operations

bit 6,3 **T3CCP<2:1>:** Timer3 and Timer1 to CCPx Enable bits
1x = Timer3 is the capture/compare clock source for the CCP modules
01 = Timer3 is the capture/compare clock source for CCP2;
Timer1 is the capture/compare clock source for CCP1
00 = Timer1 is the capture/compare clock source for the CCP modules

bit 5-4 **T3CKPS<1:0>**: Timer3 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 2 **$\overline{\text{T3SYNC}}$:** Timer3 External Clock Input Synchronization Control bit
(Not usable if the device clock comes from Timer1/Timer3.)
When TMR3CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR3CS = 0:
This bit is ignored. Timer3 uses the internal clock when TMR3CS = 0.

bit 1 **TMR3CS:** Timer3 Clock Source Select bit
1 = External clock input from Timer1 oscillator or T13CKI (on the rising edge after the first falling edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR3ON:** Timer3 On bit
1 = Enables Timer3
0 = Stops Timer3

The CCPRxH register and a 2-bit internal latch are used to double-buffer the PWM duty cycle. This double-buffering is essential for glitchless PWM operation.

When the CCPRxH and 2-bit latch match TMR2, concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCPx pin is cleared.

The maximum PWM resolution (bits) for a given PWM frequency is given by the equation:

EQUATION 15-3:

$$\text{PWM Resolution (max)} = \frac{\log\left(\frac{F_{OSC}}{F_{PWM}}\right)}{\log(2)} \text{ bits}$$

Note:	If the PWM duty cycle value is longer than the PWM period, the CCPx pin will not be cleared.

TABLE 15-4: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 40 MHz

PWM Frequency	2.44 kHz	9.77 kHz	39.06 kHz	156.25 kHz	312.50 kHz	416.67 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	FFh	FFh	FFh	3Fh	1Fh	17h
Maximum Resolution (bits)	10	10	10	8	7	6.58

15.4.3 PWM AUTO-SHUTDOWN (CCP1 ONLY)

The PWM auto-shutdown features of the Enhanced CCP module are also available to CCP1 in 28-pin devices. The operation of this feature is discussed in detail in **Section 16.4.7 “Enhanced PWM Auto-Shutdown”**.

Auto-shutdown features are not available for CCP2.

15.4.4 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPRxL register and CCPxCON<5:4> bits.
3. Make the CCPx pin an output by clearing the appropriate TRIS bit.
4. Set the TMR2 prescale value, then enable Timer2 by writing to T2CON.
5. Configure the CCPx module for PWM operation.

17.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

17.1 Master SSP (MSSP) Module Overview

The Master Synchronous Serial Port (MSSP) module is a serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D Converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)
  - Full Master mode
  - Slave mode (with general address call)

The I^2C interface supports the following modes in hardware:

- Master mode
- Multi-Master mode
- Slave mode

17.2 Control Registers

The MSSP module has three associated registers. These include a status register (SSPSTAT) and two control registers (SSPCON1 and SSPCON2). The use of these registers and their individual configuration bits differ significantly depending on whether the MSSP module is operated in SPI or I^2C mode.

Additional details are provided under the individual sections.

17.3 SPI Mode

The SPI mode allows 8 bits of data to be synchronously transmitted and received simultaneously. All four modes of SPI are supported. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) – RC5/SDO
- Serial Data In (SDI) – RC4/SDI/SDA
- Serial Clock (SCK) – RC3/SCK/SCL

Additionally, a fourth pin may be used when in a Slave mode of operation:

- Slave Select ($\overline{SS}$) – RA5/$\overline{SS}$

Figure 17-1 shows the block diagram of the MSSP module when operating in SPI mode.

FIGURE 17-1: MSSP BLOCK DIAGRAM (SPI MODE)

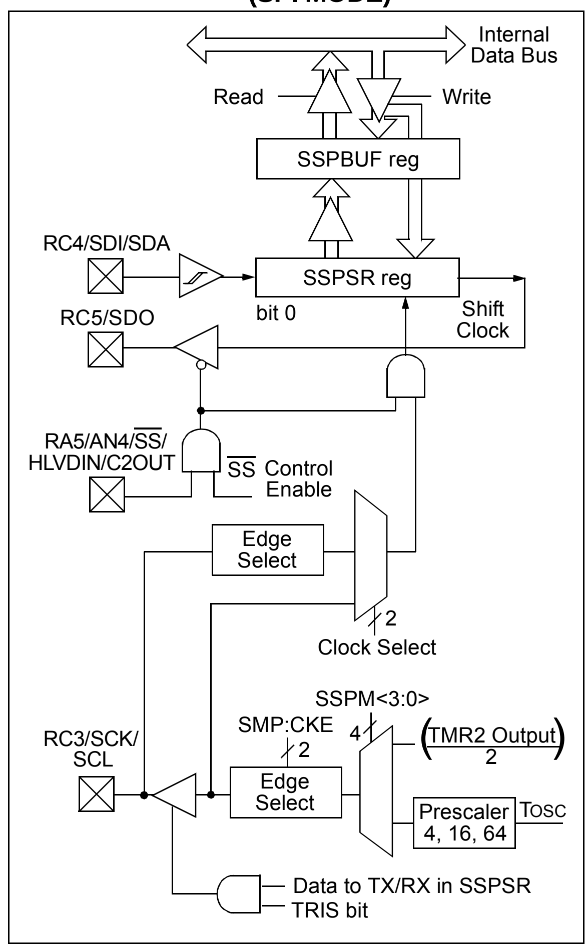


FIGURE 17-8: I²C™ SLAVE MODE TIMING WITH SEN = 0 (RECEPTION, 7-BIT ADDRESSING)

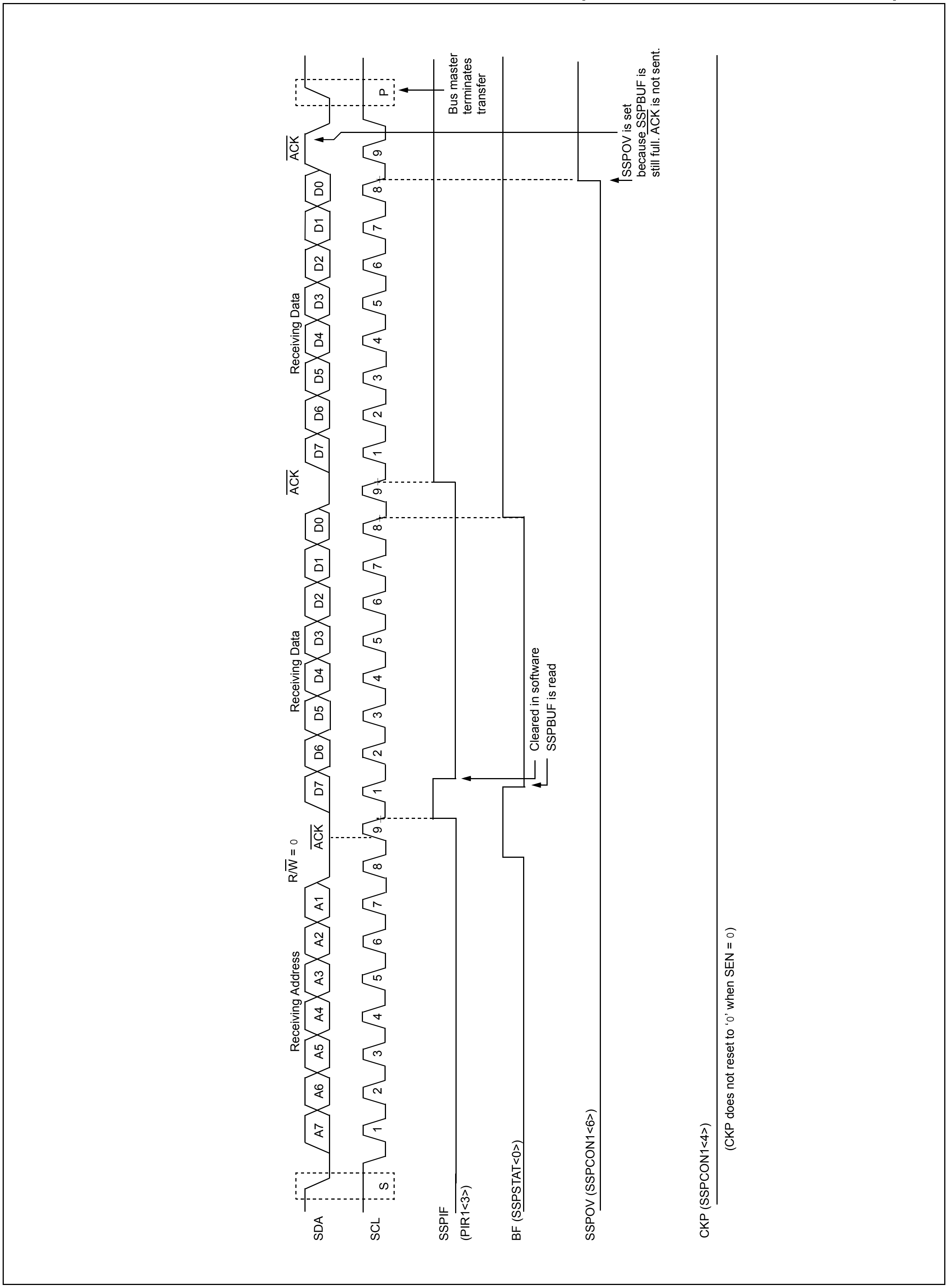
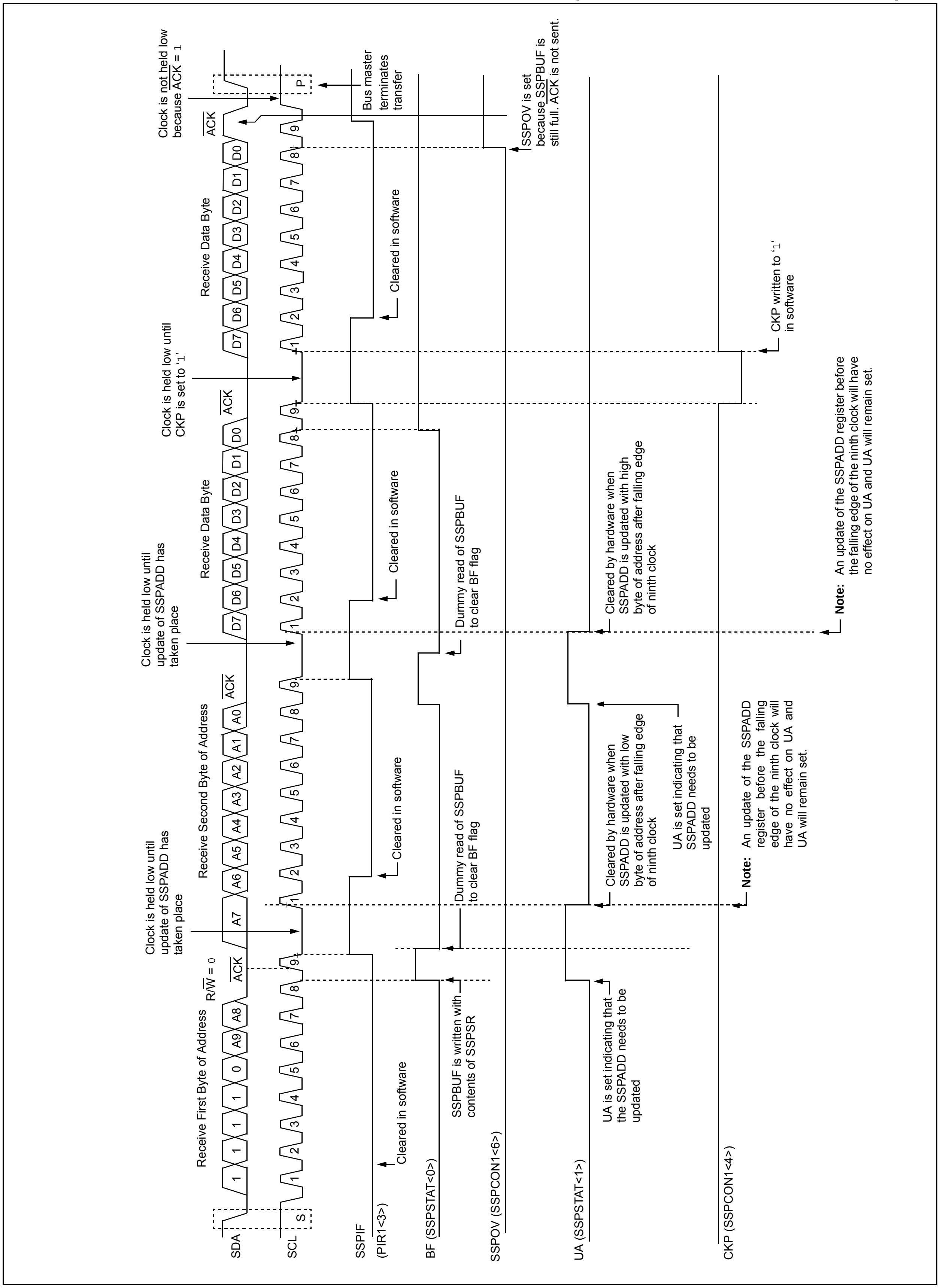


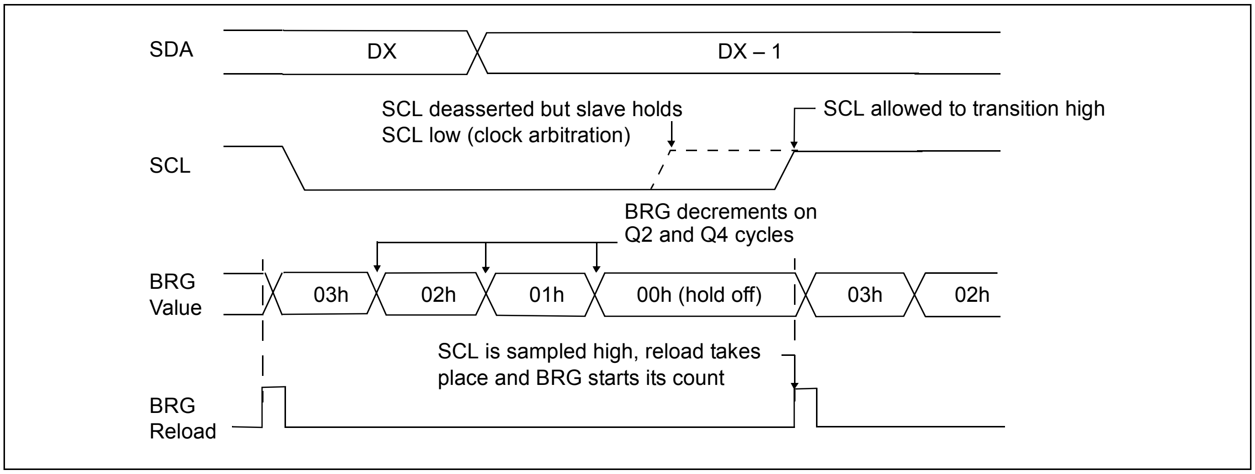
FIGURE 17-14: I²C™ SLAVE MODE TIMING WITH SEN = 1 (RECEPTION, 10-BIT ADDRESSING)



17.4.7.1 Clock Arbitration

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, deasserts the SCL pin (SCL allowed to float high). When the SCL pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCL pin is actually sampled high. When the SCL pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPADD<6:0> and begins counting. This ensures that the SCL high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 17-18).

FIGURE 17-18: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION



REGISTER 19-2: ADCON1: A/D CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-q[(1)]	R/W-q[(1)]	R/W-q[(1)]
—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5 **VCFG1:** Voltage Reference Configuration bit (VREF- source)
1 = VREF- (AN2)
0 = VSS

bit 4 **VCFG0:** Voltage Reference Configuration bit (VREF+ source)
1 = VREF+ (AN3)
0 = VDD

bit 3-0 **PCFG<3:0>:** A/D Port Configuration Control bits:

PCFG3: PCFG0	AN12	AN11	AN10	AN9	AN8	AN7[(2)]	AN6[(2)]	AN5[(2)]	AN4	AN3	AN2	AN1	AN0
0000[(1)]	A	A	A	A	A	A	A	A	A	A	A	A	A
0001	A	A	A	A	A	A	A	A	A	A	A	A	A
0010	A	A	A	A	A	A	A	A	A	A	A	A	A
0011	D	A	A	A	A	A	A	A	A	A	A	A	A
0100	D	D	A	A	A	A	A	A	A	A	A	A	A
0101	D	D	D	A	A	A	A	A	A	A	A	A	A
0110	D	D	D	D	A	A	A	A	A	A	A	A	A
0111[(1)]	D	D	D	D	D	A	A	A	A	A	A	A	A
1000	D	D	D	D	D	D	A	A	A	A	A	A	A
1001	D	D	D	D	D	D	D	A	A	A	A	A	A
1010	D	D	D	D	D	D	D	D	A	A	A	A	A
1011	D	D	D	D	D	D	D	D	D	A	A	A	A
1100	D	D	D	D	D	D	D	D	D	D	A	A	A
1101	D	D	D	D	D	D	D	D	D	D	D	A	A
1110	D	D	D	D	D	D	D	D	D	D	D	D	A
1111	D	D	D	D	D	D	D	D	D	D	D	D	D

A = Analog input D = Digital I/O

Note 1: The POR value of the PCFG bits depends on the value of the PBADEN Configuration bit. When PBADEN = 1, PCFG<2:0> = 000; when PBADEN = 0, PCFG<2:0> = 111.

2: AN5 through AN7 are available only on 40/44-pin devices.

The value in the ADRESH:ADRESL registers is not modified for a Power-on Reset. The ADRESH:ADRESL registers will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 19.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/$\overline{\text{DONE}}$ bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0 register)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit, ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 19-2: A/D TRANSFER FUNCTION

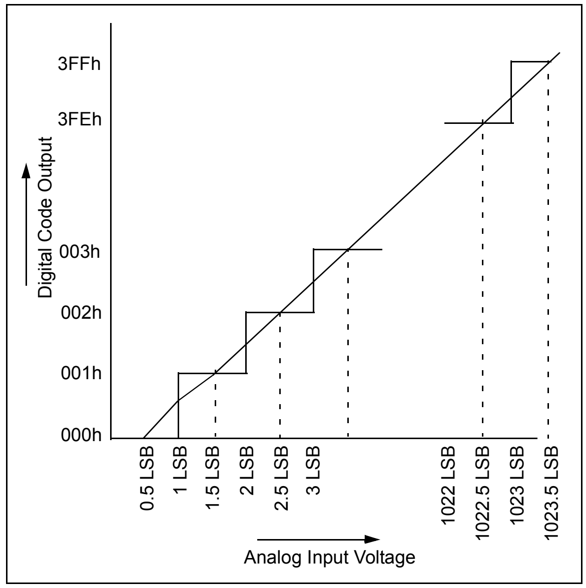
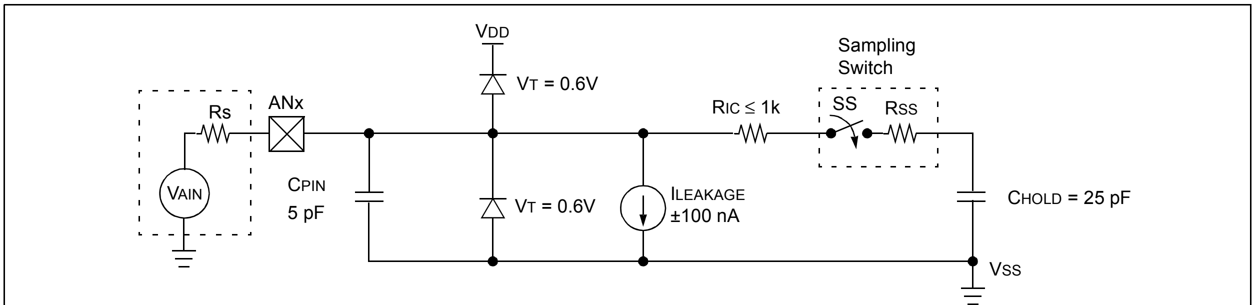


FIGURE 19-3: ANALOG INPUT MODEL



Legend:	CPIN	= Input Capacitance
	VT	= Threshold Voltage
	ILEAKAGE	= Leakage Current at the pin due to various junctions
	RIC	= Interconnect Resistance
	SS	= Sampling Switch
	CHOLD	= Sample/Hold Capacitance (from DAC)
	RSS	= Sampling Switch Resistance

22.2 HLVD Setup

The following steps are needed to set up the HLVD module:

1. Write the value to the HLVDL<3:0> bits that selects the desired HLVD trip point.
2. Set the VDIRMAG bit to detect high voltage (VDIRMAG = `1`) or low voltage (VDIRMAG = `0`).
3. Enable the HLVD module by setting the HLVDEN bit.
4. Clear the HLVD interrupt flag (PIR2<2>), which may have been set from a previous interrupt.
5. Enable the HLVD interrupt, if interrupts are desired, by setting the HLVDIE and GIE bits (PIE2<2> and INTCON<7>). An interrupt will not be generated until the IRVST bit is set.

22.3 Current Consumption

When the module is enabled, the HLVD comparator and voltage divider are enabled and will consume static current. The total current consumption, when enabled, is specified in electrical specification parameter D022B.

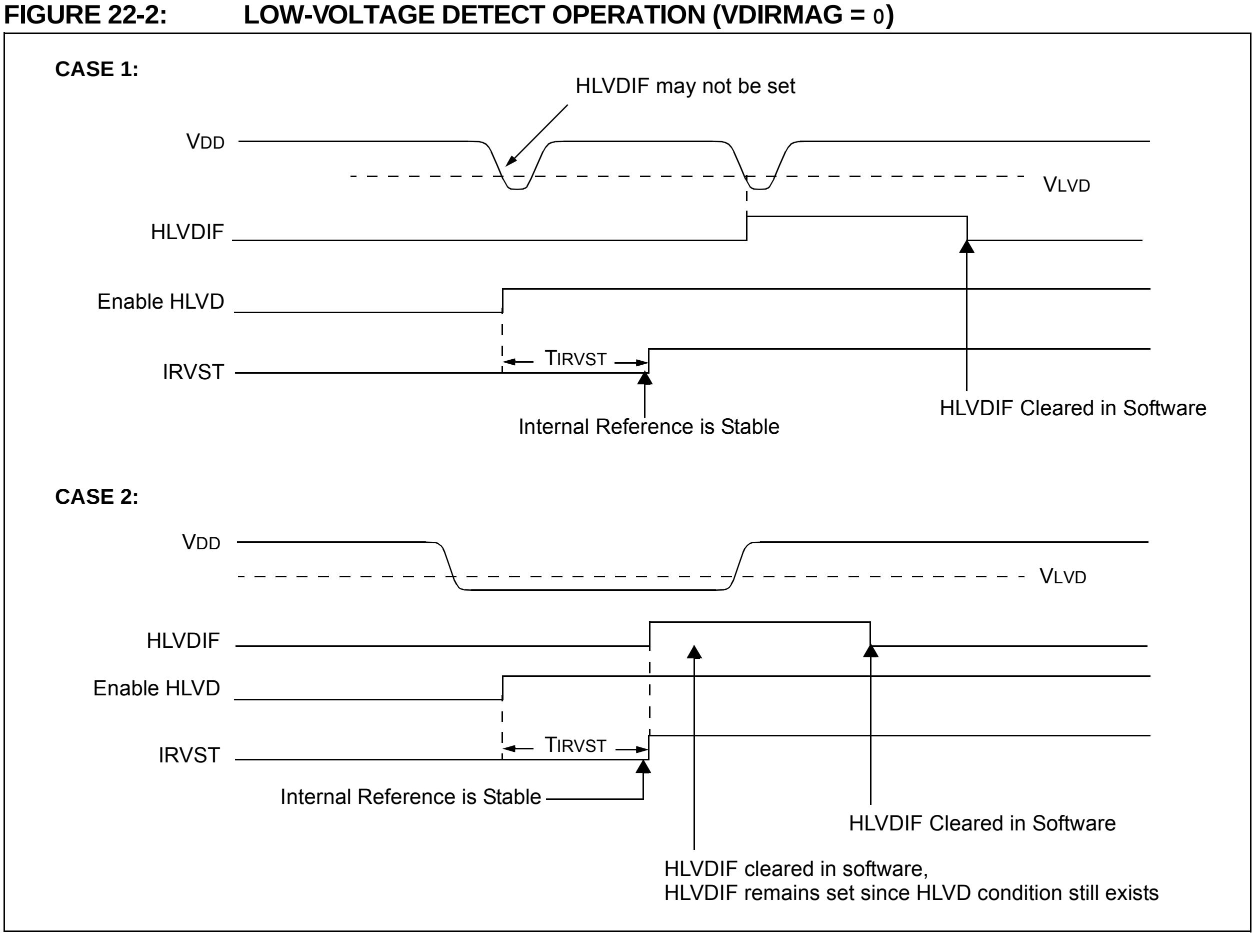
Depending on the application, the HLVD module does not need to be operating constantly. To decrease the current requirements, the HLVD circuitry may only need to be enabled for short periods where the voltage is checked. After doing the check, the HLVD module may be disabled.

22.4 HLVD Start-up Time

The internal reference voltage of the HLVD module, specified in electrical specification parameter D420, may be used by other internal circuitry, such as the programmable Brown-out Reset. If the HLVD or other circuits using the voltage reference are disabled to lower the device's current consumption, the reference voltage circuit will require time to become stable before a low or high-voltage condition can be reliably detected. This start-up time, T_{IRVST}, is an interval that is independent of device clock speed. It is specified in electrical specification parameter 36.

The HLVD interrupt flag is not enabled until T_{IRVST} has expired and a stable reference voltage is reached. For this reason, brief excursions beyond the set point may not be detected during this interval (refer to Figure 22-2 or Figure 22-3).

FIGURE 22-2: LOW-VOLTAGE DETECT OPERATION (VDIRMAG = `0`)



MULLW — Multiply Literal with W

Syntax:	MULLW k
Operands:	$0 \le k \le 255$
Operation:	(W) x k $\rightarrow$ PRODH:PRODL
Status Affected:	None
Encoding:	`0000` `1101` `kkkk` `kkkk`
Description:	An unsigned multiplication is carried out between the contents of W and the 8-bit literal 'k'. The 16-bit result is placed in the PRODH:PRODL register pair. PRODH contains the high byte. W is unchanged. None of the Status flags are affected. Note that neither Overflow nor Carry is possible in this operation. A zero result is possible but not detected.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write registers PRODH: PRODL

Example: `MULLW 0C4h`

Before Instruction

W = E2h
PRODH = ?
PRODL = ?

After Instruction

W = E2h
PRODH = ADh
PRODL = 08h

MULWF — Multiply W with f

Syntax:	MULWF f {,a}
Operands:	$0 \le f \le 255$ $a \in [0,1]$
Operation:	(W) x (f) $\rightarrow$ PRODH:PRODL
Status Affected:	None
Encoding:	`0000` `001a` `ffff` `ffff`
Description:	An unsigned multiplication is carried out between the contents of W and the register file location 'f'. The 16-bit result is stored in the PRODH:PRODL register pair. PRODH contains the high byte. Both W and 'f' are unchanged. None of the Status flags are affected. Note that neither Overflow nor Carry is possible in this operation. A zero result is possible but not detected. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default). If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write registers PRODH: PRODL

Example: `MULWF REG, 1`

Before Instruction

W = C4h
REG = B5h
PRODH = ?
PRODL = ?

After Instruction

W = C4h
REG = B5h
PRODH = 8Ah
PRODL = 94h

POP — Pop Top of Return Stack

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:

```
POP
GOTO    NEW
```

Before Instruction
- TOS = 0031A2h
- Stack (1 level down) = 014332h

After Instruction
- TOS = 014332h
- PC = NEW

PUSH — Push Top of Return Stack

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:

```
PUSH
```

Before Instruction
- TOS = 345Ah
- PC = 0124h

After Instruction
- PC = 0126h
- TOS = 0126h
- Stack (1 level down) = 345Ah

SUBFSR **Subtract Literal from FSR**

Syntax:	SUBFSR f, k
Operands:	0 ≤ k ≤ 63 f ∈ [0, 1, 2]
Operation:	FSR(f) – k → FSRf
Status Affected:	None
Encoding:	`1110` `1001` `ffkk` `kkkk`
Description:	The 6-bit literal ‘k’ is subtracted from the contents of the FSR specified by ‘f’.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: `SUBFSR 2, 23h`

Before Instruction
FSR2 = 03FFh

After Instruction
FSR2 = 03DCh

SUBULNK **Subtract Literal from FSR2 and Return**

Syntax:	SUBULNK k
Operands:	0 ≤ k ≤ 63
Operation:	FSR2 – k → FSR2, (TOS) → PC
Status Affected:	None
Encoding:	`1110` `1001` `11kk` `kkkk`
Description:	The 6-bit literal ‘k’ is subtracted from the contents of the FSR2. A `RETURN` is then executed by loading the PC with the TOS. The instruction takes two cycles to execute; a `NOP` is performed during the second cycle. This may be thought of as a special case of the `SUBFSR` instruction, where f = 3 (binary ‘`11`’); it operates only on FSR2.
Words:	1
Cycles:	2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination
No Operation	No Operation	No Operation	No Operation

Example: `SUBULNK 23h`

Before Instruction
FSR2 = 03FFh
PC = 0100h

After Instruction
FSR2 = 03DCh
PC = (TOS)

TABLE 26-21: MASTER SSP I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
102	TR	SDA and SCL Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
103	TF	SDA and SCL Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: Maximum pin capacitance = 10 pF for all I²C pins.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but parameter 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line, parameter 102 + parameter 107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCL line is released.

FIGURE 27-15: MAXIMUM IDD ACROSS VDD (RC_IDLE MODE, -40°C TO +85°C)

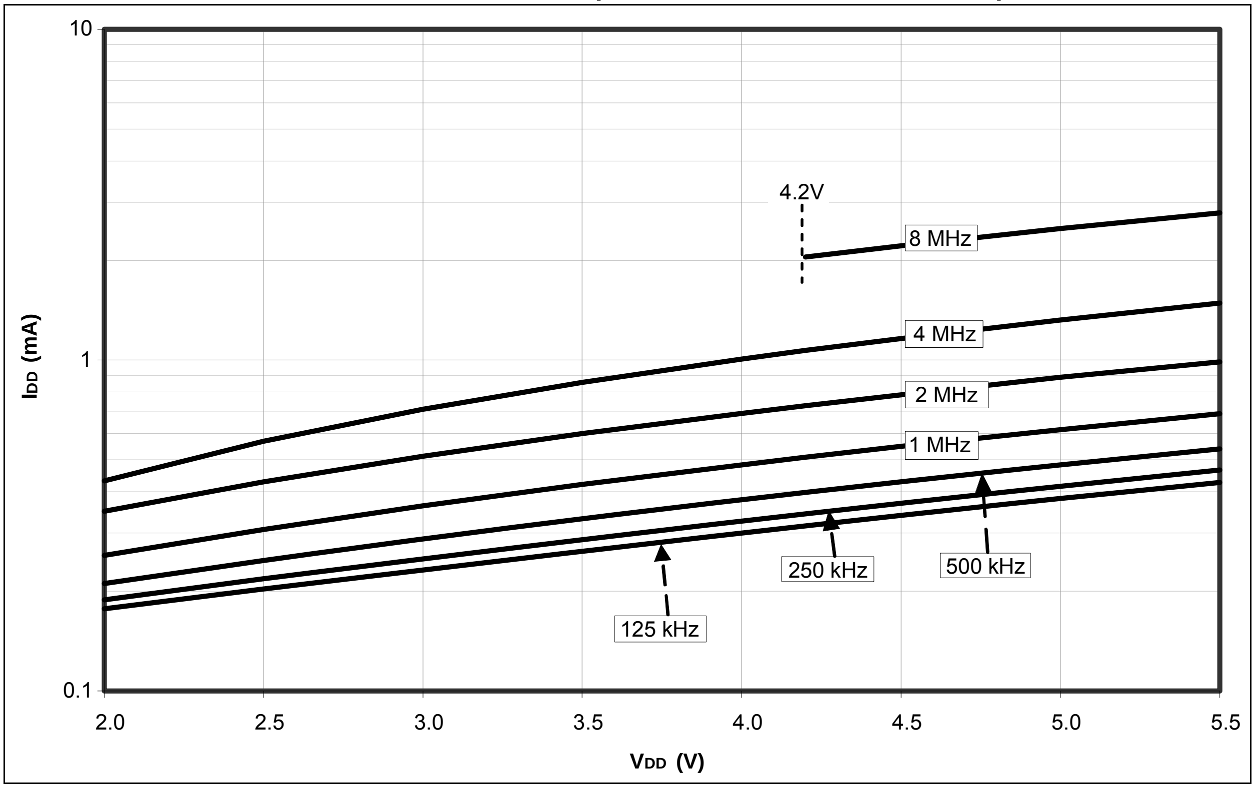


FIGURE 27-16: TYPICAL AND MAXIMUM IDD ACROSS VDD (RC_IDLE MODE, 31 kHz)

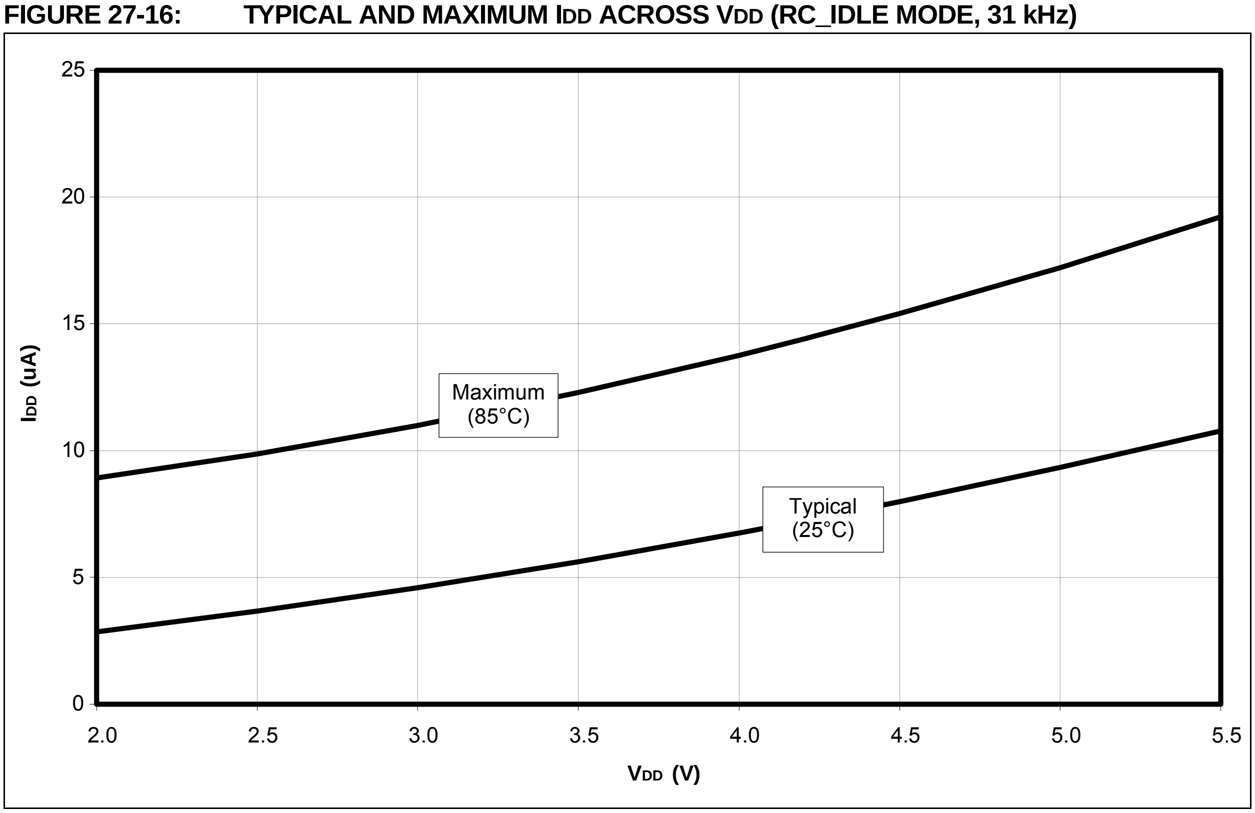


FIGURE 27-37: INTOSC FREQUENCY vs. VDD, TEMPERATURE (-40°C, +25°C, +85°C, +125°C)

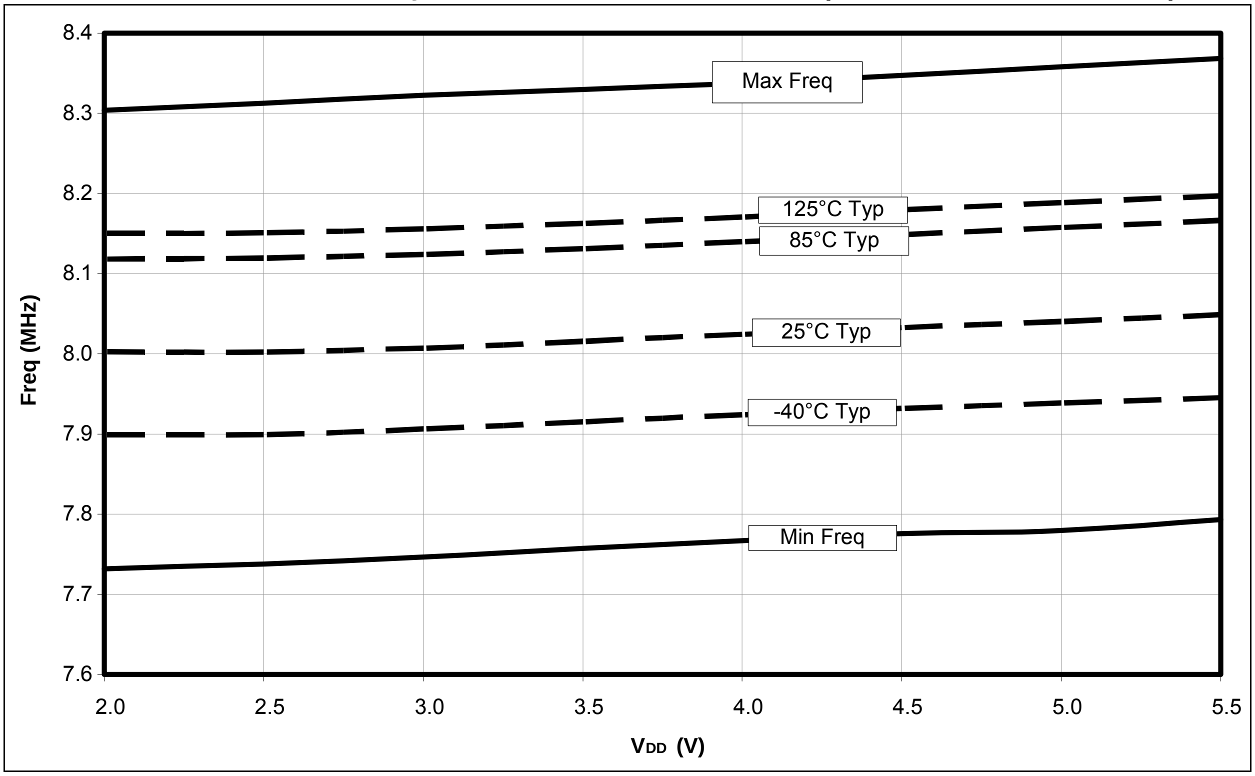
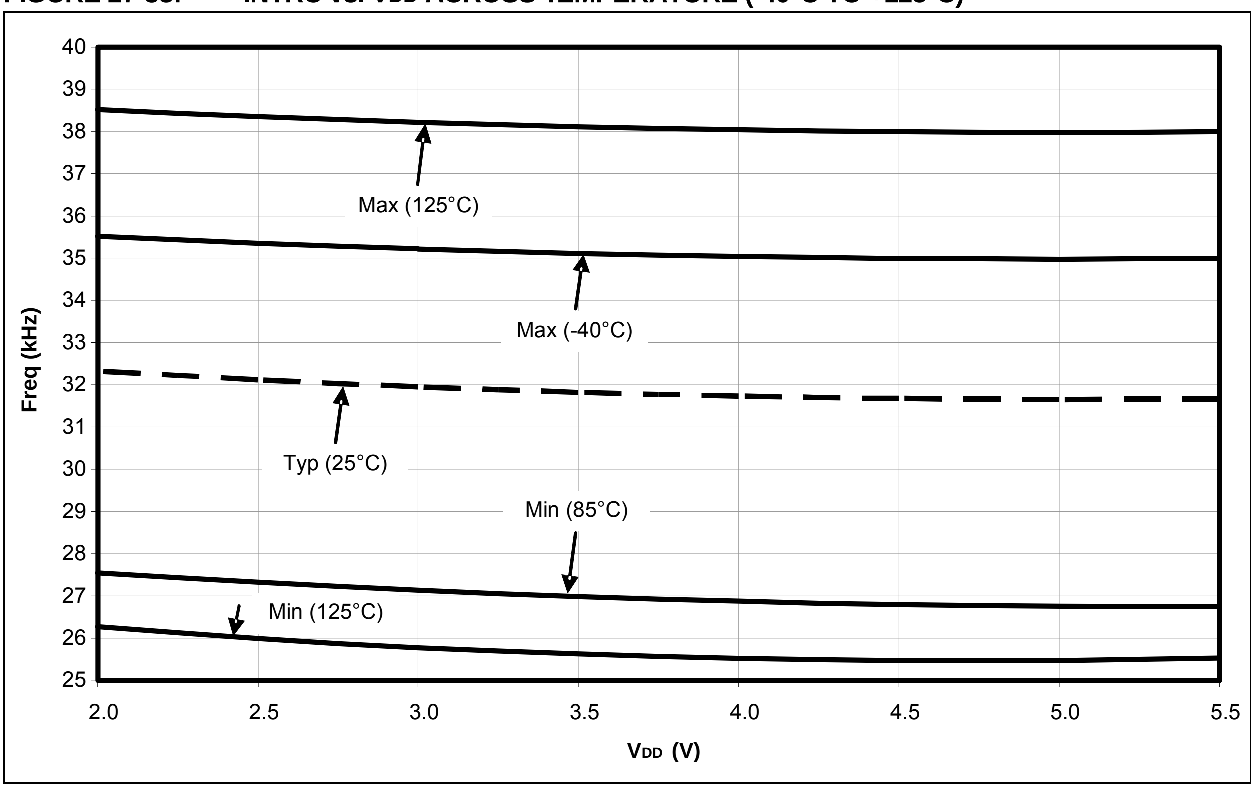


FIGURE 27-38: INTRC vs. VDD ACROSS TEMPERATURE (-40°C TO +125°C)



APPENDIX A: REVISION HISTORY

Revision A (June 2004)

Original data sheet for PIC18F2420/2520/4420/4520 devices.

Revision B (January 2007)

This revision includes updates to the packaging diagrams.

Revision C (June 2007)

This revision includes updates to **Section 6.0 "Flash Program Memory"**, **Section 23.0 "Special Features of the CPU"**, **Section 26.0 "Electrical Characteristics"** and minor corrections applicable to Timer1, EUSART and the packaging diagrams. Also added the 125°C specifications.

Revision D (July 2007)

This revision updated the extended temperature information in **Section 26.0 "Electrical Characteristics"**.

Revision E (October 2008)

This revision updated **Section 26.0 "Electrical Characteristics"**, **Section 27.0 "DC and AC Characteristics Graphs and Tables"** and **Section 28.0 "Packaging Information"**.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F2420	PIC18F2520	PIC18F4420	PIC18F4520
Program Memory (Bytes)	16384	32768	16384	32768
Program Memory (Instructions)	8192	16384	8192	16384
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/PWM Modules	0	0	1	1
Parallel Communications (PSP)	No	No	Yes	Yes
10-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Packages	28-Pin SPDIP 28-Pin SOIC 28-Pin QFN	28-Pin SPDIP 28-Pin SOIC 28-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN